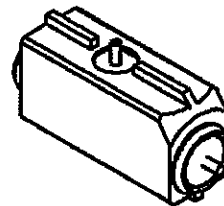
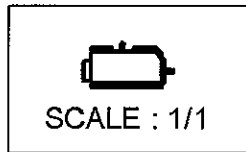
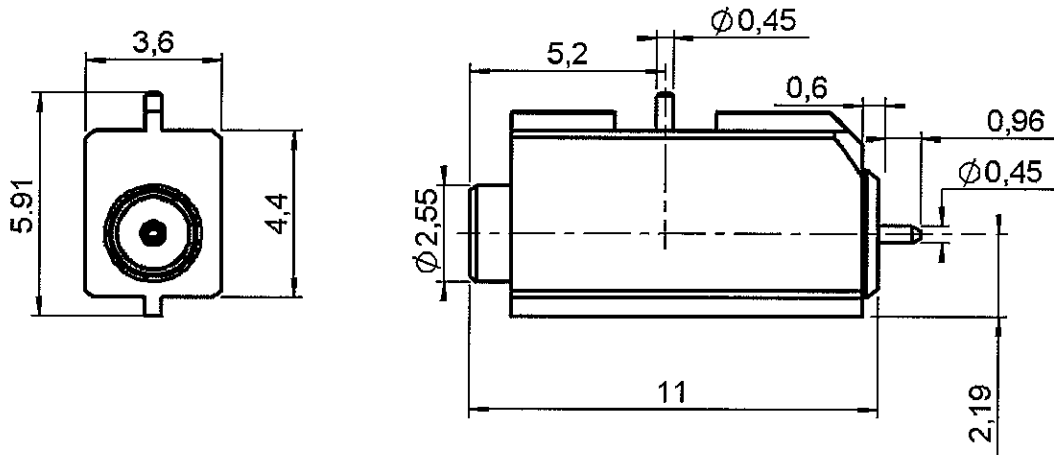


SMT SWITCH RECEPTACLE

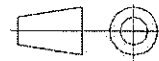
R199.005.890

REEL OF 500

Series : MC-CARD



All dimensions are in mm.



COMPONENTS	MATERIALS	PLATINGS (µm)
BODY	BRASS	GOLD 0.2 OVER NICKEL 2
CENTER CONTACT	BERYLLIUM COPPER	GOLD 0.8 OVER NICKEL 2
OUTER CONTACT	-	-
INSULATOR	POLYETHER ETHERCETONE 30% GF	-
GASKET	-	-
OTHERS PARTS	STAINLESS STEEL	-
-	-	-
-	-	-

Issue : 0541 D

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



SMT SWITCH RECEPTACLE

R199.005.890

REEL OF 500

Series : MC-CARD

PACKAGING

SPECIFICATION

Standard	Unit	Other
500	'W' option	Contact us

* 1.4 max at 2.5 GHz. 00

ELECTRICAL CHARACTERISTICS

ENVIRONMENTAL

Impedance **50** Ω
 Frequency **0-3** GHz
 VSWR **1.4*** + **0.000** x F(GHz) Maxi
 Insertion loss **0.3**** √F(GHz) dB Maxi
 RF leakage - (- F(GHz)) dB Maxi
 Voltage rating **100** Veff Maxi
 Dielectric withstanding voltage **250** Veff mini
 Insulation resistance **5000** MΩ mini

Operating temperature **-40/+110** °C
 Hermetic seal - Atm.cm3/s
 Panel leakage -

OTHERS CHARACTERISTICS

Assembly instruction **NA**

Others :
 isol between 2 ways: -22dBmin at 2.5 GHz

MECHANICAL CHARACTERISTICS

Center contact retention
 Axial force – Mating end - N mini
 Axial force – Opposite end - N mini
 Torque - N.cm mini

Recommended torque
 Mating - N.cm
 Panel nut - N.cm

Mating life **5000** Cycles mini
 Weight **0.985** g

Issue : 0541 D

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SMT SWITCH RECEPTACLE

REEL OF 500

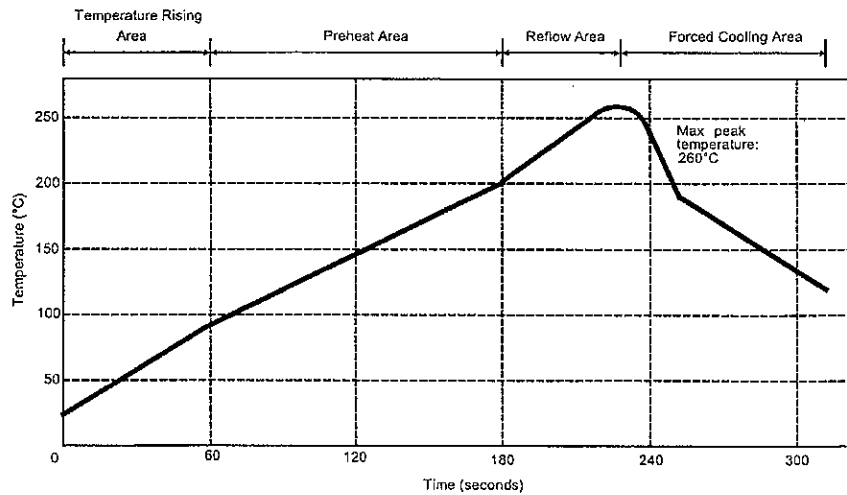
R199.005.890

Series : MC-CARD

SOLDER PROCEDURE

1. Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
We advise a thickness of 150 microns (5.850 microinch). Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.
Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.
3. Soldering by infra-red reflow.
Below, please find the typical profile to use.
4. Cleaning of printed circuit boards.
5. Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

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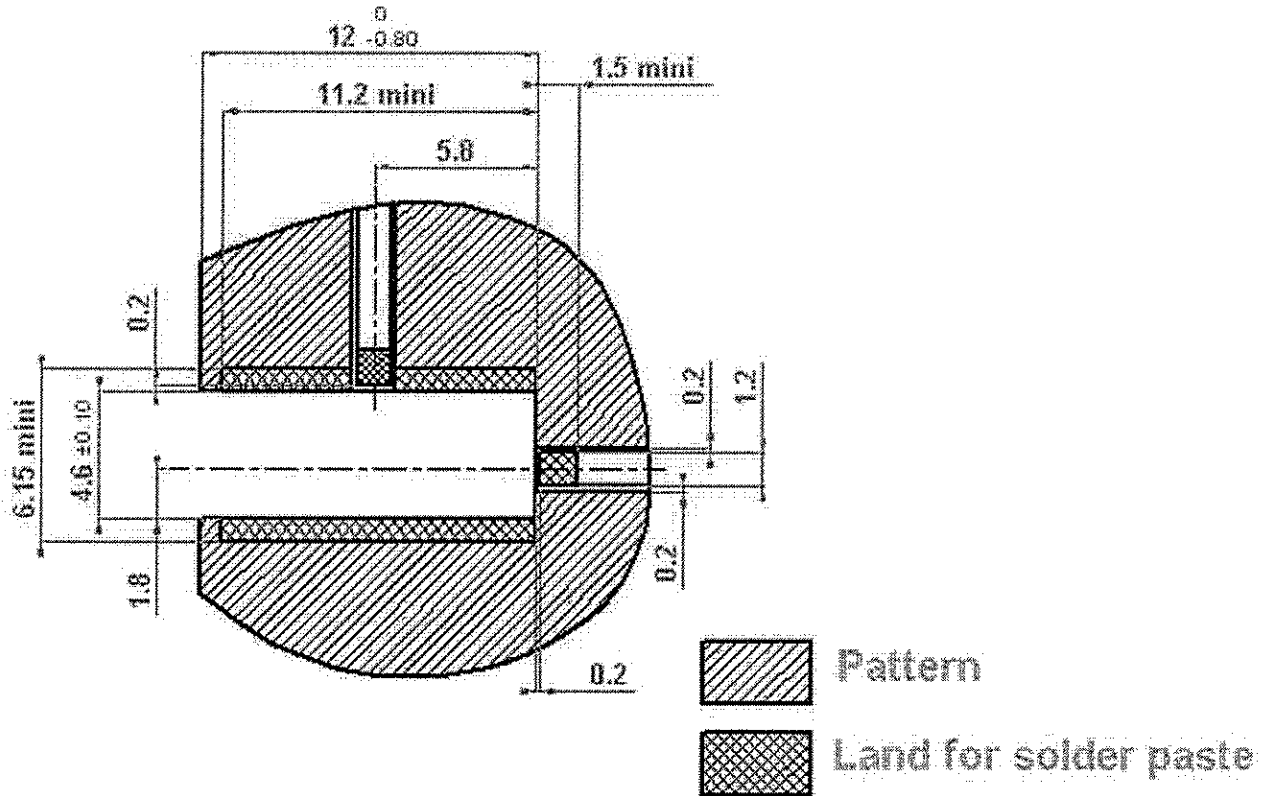
SMT SWITCH RECEPTACLE

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REEL OF 500

Series : MC-CARD

INFORMATIONS



COPLANAR LINE :

Ground and signal are on the same side.

Thickness of PCB : 1 mm.

The material of PCB is glass – epoxy composite (Er=4.8)

The solder resist should be printed except for the land pattern of the PCB.

Issue : 0541 D

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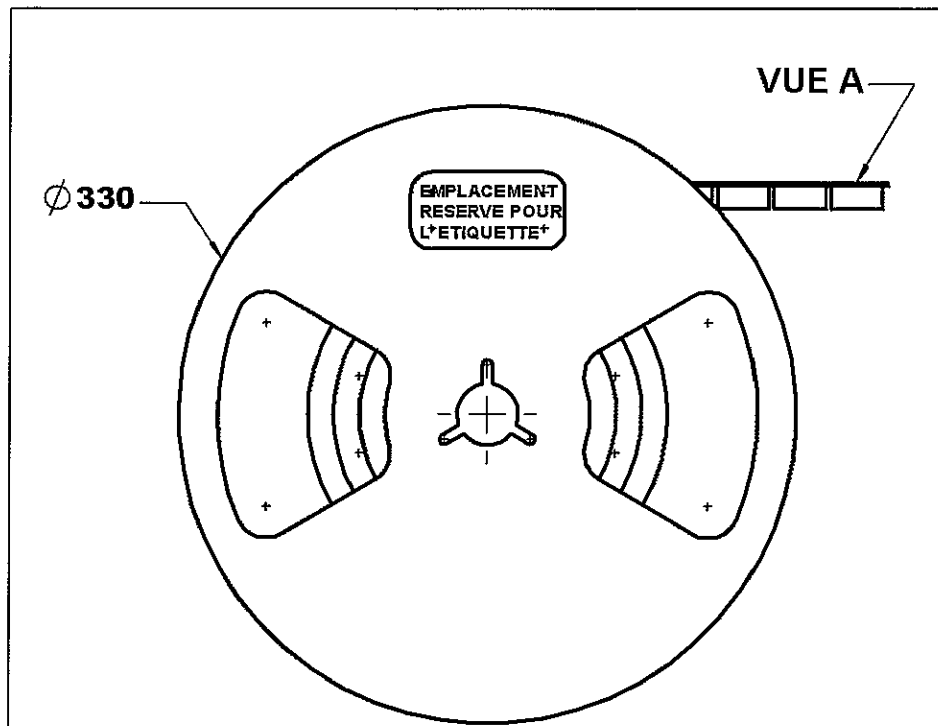
SMT SWITCH RECEPTACLE

R199.005.890

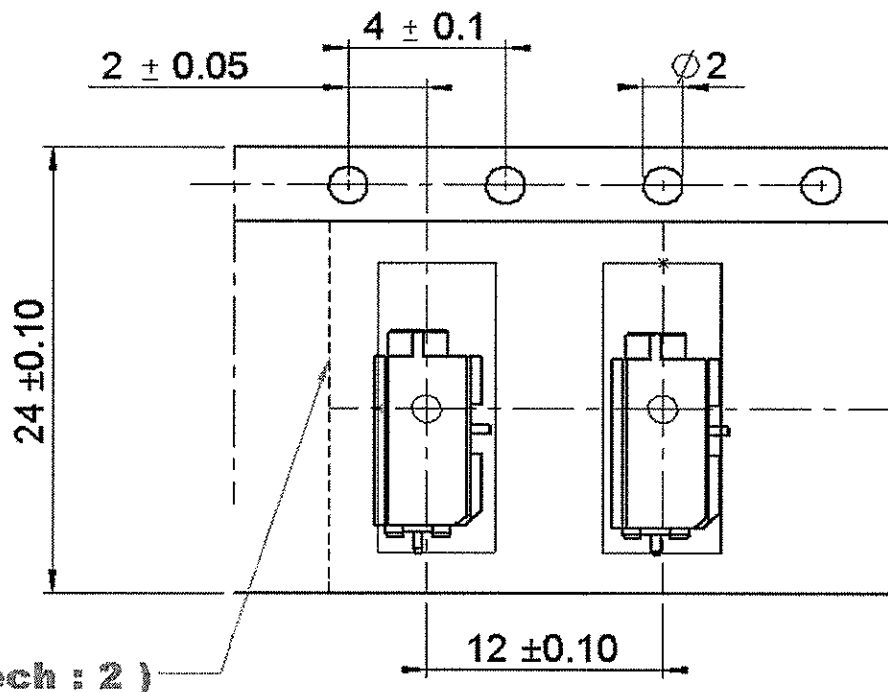
REEL OF 500

Series : MC-CARD

PACKAGING



bobine Ech : 0.7



Vue A (ech : 2)

Issue : 0541 D

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